

Taiwan Semiconductor

# 1A, 100V - 200V Ultra Fast Surface Mount Rectifier

### **FEATURES**

- Planar technology
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

### **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

### **MECHANICAL DATA**

- Case: Micro SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.006g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I <sub>F</sub>	1	А
V <sub>RRM</sub>	100 - 200	V
I <sub>FSM</sub>	28	А
T <sub>J MAX</sub>	175	°C
Package	Micro SMA	
Configuration	Single	e die





Micro SMA



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	PU1BM	PU1DM	UNIT
Marking code on the device			P5	P6	
Repetitive peak reverse voltage		V <sub>RRM</sub>	100	200	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	70	140	V
Forward current		I <sub>F</sub>	1		А
Surge peak forward current, single half sine-	t = 8.3ms			8	А
wave superimposed on rated load	t = 1.0ms	I <sub>FSM</sub>	52		Α
Junction temperature		TJ	-55 to +175		°C
Storage temperature		T <sub>STG</sub>	-55 to +175		°C



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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-lead thermal resistance	R <sub>ƏJL</sub>	28	°C/W
Junction-to-ambient thermal resistance	R <sub>⊖JA</sub>	60	°C/W
Junction-to-case thermal resistance	R <sub>θJC</sub>	34	°C/W

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage <sup>(1)</sup>	$I_F = 0.5A, T_J = 25^{\circ}C$		0.84	-	V
	$I_F = 1.0A, T_J = 25^{\circ}C$	V	0.90	1.05	V
	$I_F = 0.5A, T_J = 125^{\circ}C$	- V <sub>F</sub>	0.70	-	V
	$I_F = 1.0A, T_J = 125^{\circ}C$		0.76	0.90	V
Reverse current @ rated $V_R^{(2)}$	$T_J = 25^{\circ}C$	I <sub>R</sub>	-	1	μA
	T <sub>J</sub> = 125°C		-	15	μA
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	1	-	25	ns
	$I_F = 1.0A$ , di/dt = 50 A/µs, $V_R = 30V$	- t <sub>rr</sub>	36	-	ns
Reverse recovery current		I <sub>RM</sub>	3.4	-	Α
Reverse recovery charge	I <sub>F</sub> = 1.0A, di/dt = 200 A/μs, V <sub>R</sub> = 100V	Q <sub>rr</sub>	40	-	nC
Reverse recovery time		t <sub>rr</sub>	24	-	ns
Junction capacitance	1MHz, V <sub>R</sub> = $4.0$ V	CJ	18	-	pF

### Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
PU1xM	Micro SMA	12,000 / Tape & Reel

Notes:

1. "x" defines voltage from 100V(PU1BM) to 200V(PU1DM)



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

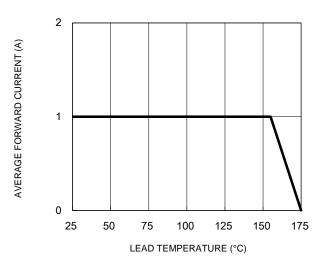
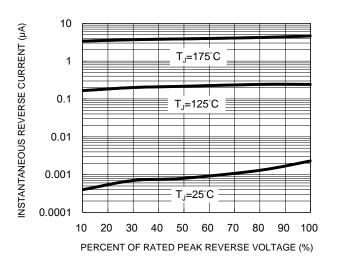


Fig.1 Forward Current Derating Curve

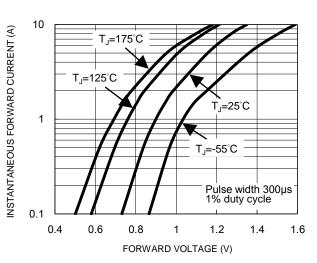
### Fig.3 Typical Reverse Characteristics

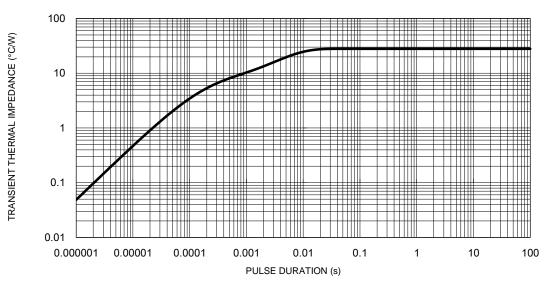


# $(10) \\ (10) \\ 10 \\ (10) \\ (1$

### Fig.2 Typical Junction Capacitance





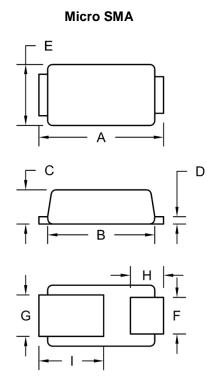


### Fig.5 Typical Transient Thermal Impedance

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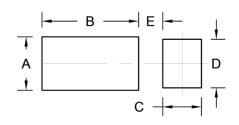


### **PACKAGE OUTLINE DIMENSIONS**



DIM.	Unit (mm)		Unit	(inch)
Divi.	Min.	Max.	Min.	Max.
А	2.30	2.70	0.091	0.106
В	2.10	2.30	0.083	0.091
С	0.63	0.73	0.025	0.029
D	0.10	0.20	0.004	0.008
E	1.15	1.35	0.045	0.053
F	0.65	0.85	0.026	0.034
G	0.75	0.95	0.030	0.037
Н	0.55	0.75	0.022	0.030
I	1.10	1.50	0.043	0.059

## SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.10	0.043
В	2.00	0.079
С	0.80	0.031
D	1.00	0.039
E	0.50	0.020

### **MARKING DIAGRAM**



P/N	= Marking Code
YW	= Data Code



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